Product End-of-Life Disassembly Instructions

Product Category: Personal Computers
Marketing Name / Model **[List multiple models if applicable.]**
HP TouchSmart 610 PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Volume board,Rear IO board,Wireless module,Convertor board,MXM module,Scalar board,B-CAS module,Memory module*2,Mother board	10
Batteries	All types including standard alkaline and lithium coin or button style batteries Coin cell battery	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LCD panel	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #Screwdiver	
Description #2	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand base cover
2. Release screws and remove Stand base assy
3. Open Rear IO door and remove Dongel cover
4. Remove Access door screw covers
5. Release screws and remove Access doors R/L assy
6. Release screws and remove Sidecap R assy
7. Release screws and remove Sidecap L assy
8. Release screw and remove Volume board (figure.1)
9. Relase screws and Remove T-cover assy
10. Release screws and remove Rear IO module
11. Release screws and remove Rear IO board (figure.2)
12. Release captive screw and remove ODD module
13. Release screw and remove ODD board
14. Release screws and remove Rear frame
15. Release screws and remove Stand rail assy
16. Release screws and remove MB shielding assy
17. Release screws and remove Wireless module (figure.3)
18. Release screws and remove Convertor board (figure.4)
19. Release captive screws and remove Thermal module
20. Release screws and remove MXM module (figure.5)
21. Release screws and remove Scalar module
22. Release screws and remove Scalar board (figure.6)
23. Release screws and remove B-CAS module (figure.7)
24. Release screws and remove Memory module (figure.8)
25. Release screws and remove Mother board (figure.9)
26. Release captive screws and remove HDD module
27. Release screws and remove Speaker modules
28. Release screws and remove System fan
29. Release screws and remove Webcam module
30. Release screws and remove DMIC modules
31. Release screws and remove Main frame assy
32. Release screws and remove TSP module
33. Release screws and remove LCD brackets
34. Touch glass disassembly(Figure 10)

35. LCD panel disassembly(Figure 11)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Volume board

2. Rear IO board

3. Wireless module

4. Convertor board

PSG instructions for this template are available at EL-MF877-01

5. MXM module

6. Scalar board

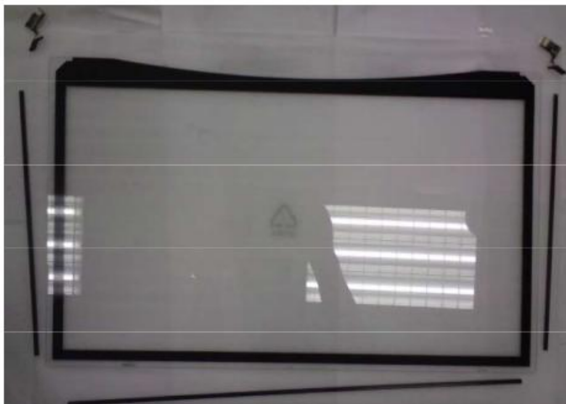
7. B-CAS module

8. Memory module

9. Mother board

10. Touch panel glass disassembly

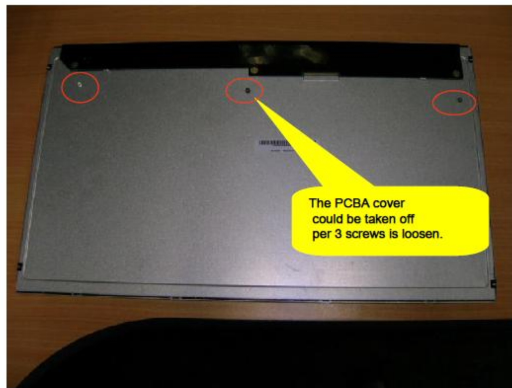
Panel with touch panel glass



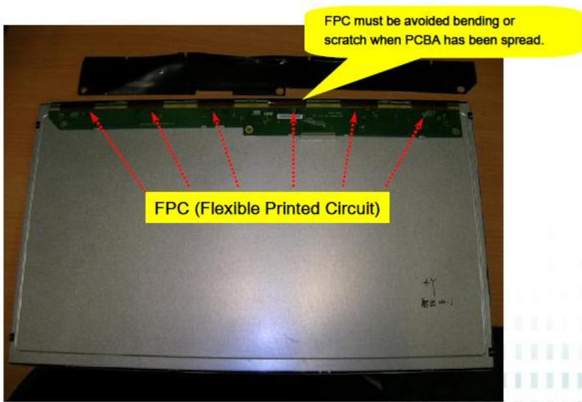
Touch panel glass

11. LCD panel disassembly process

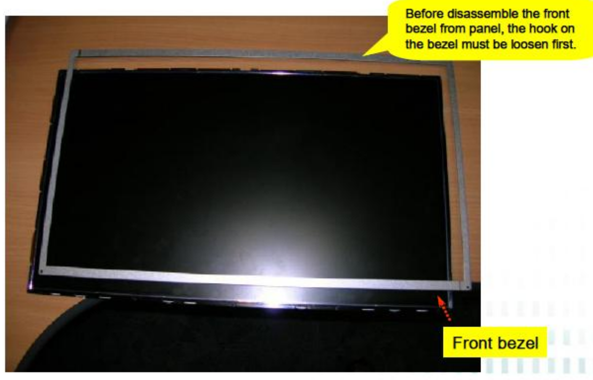
1.Remove screws in the shielding plat of panel



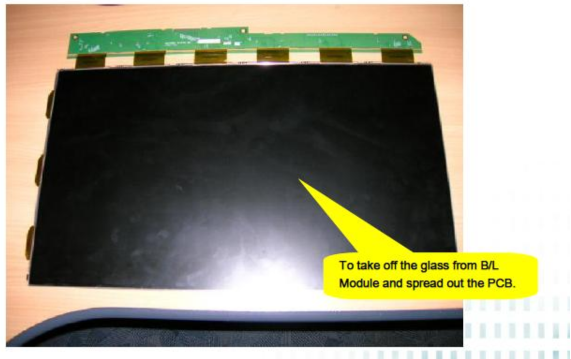
2. Tear off the PCBA mylar



3.Remove the front bezel



4. Take off the TFT glass from B/L module



5. Take off frame from B/L module

6. Separate optical layers of B/L module

7. Take off LED light bar from B/L module